METHOD, STRUCTURE, AND COMPUTER PROGRAM PRODUCT FOR IMPLEMENTING HIGH FREQUENCY RETURN CURRENT PATHS WITHIN ELECTRONIC PACKAGES

Abstract of the Disclosure

A method, structure and computer program product are provided for implementing high frequency return current paths within electronic packages. Electronic package physical design data is received for identifying a design layout. For each of a plurality of cells in a grid of a set cell size within the identified design layout, a respective number of signal vias, reference voltage vias, and ground vias are identified. A signal to reference via ratio is calculated for each of the plurality of cells. Each cell having a calculated signal to reference via ratio greater than a target ratio is identified. Vias are selectively added within each of the identified cells for providing high frequency return current paths.